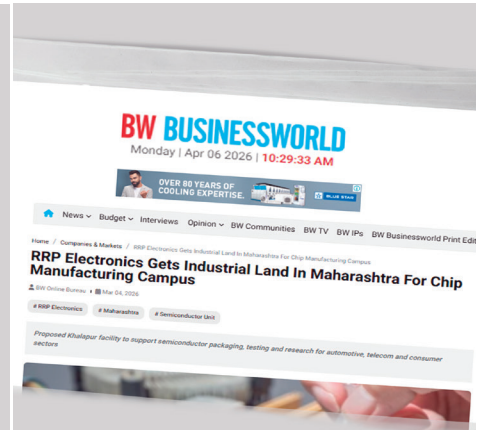


# FRONTIER





# RRP Electronics Ltd. Secures 101-Acre Industrial Land in Maharashtra for Proposed Semiconductor Manufacturing Campus

A site in Khalapur is earmarked for integrated semiconductor packaging, wafer-level packaging, and potential fabrication facilities.

RRP Electronics Ltd. has secured an industrial land parcel in Maharashtra for developing a large-scale semiconductor manufacturing and advanced packaging campus. The company announced the allocation of Industrial Plot No. A-1, spanning approximately 101 acres (about 410,000 square meters), in the Khalapur Phase-3 and Expansion Industrial Area.

This development is planned to accommodate multiple Outsourced Semiconductor Assembly and Testing (OSAT) production lines, advanced wafer-level packaging (WLP) facilities, and potential semiconductor fabrication units, subject to requisite approvals. The campus is expected to support manufacturing activities serving sectors such as automotive, industrial electronics, telecommunications, and consumer applications.

“ The allocation of this ~101-acre land parcel at Khalapur is a foundational step in RRP Electronics’ journey to build a large-scale, integrated semiconductor manufacturing campus in Maharashtra. ”

said Mr. Rajendra Chodankar, Founder and Chairman of RRP Electronics Ltd. He added that the phased development aligns with the India Semiconductor Mission and the Atmanirbhar Bharat initiative, supporting the localization of a larger portion of the semiconductor value chain within the country.

Headquartered in Navi Mumbai, RRP Electronics Ltd. is the first company to establish an OSAT facility in Maharashtra.



## RRP Electronics Ltd. Team Visits Taiwan for Advanced Semiconductor Packaging Training

The technology transfer program supports capability building in advanced packaging processes.

Recently, a team from RRP Electronics Ltd. visited Taiwan as part of a technology transfer program centred on cutting-edge semiconductor packaging methods, with the aim to strengthen the company's internal expertise through hands-on training and technical knowledge development.

The team, led by Mrs. Aparna Kadam, general manager, included Ms. Sakshi Nishane, Mr. Harshwardhan Jadhav, Mr. Nayan Patel, Mr. Shreyash Pashilkar, Mr. Siva Kumar, and Mr. Balasubramaniam. The group represented a cross-functional mix of process engineers, quality control engineers, and design engineers.

During the visit, the engineers engaged with HorngCom Technology Co. Ltd. a Taiwan-based semiconductor company specializing in advanced packaging solutions and high-precision semiconductor manufacturing. The program involved detailed knowledge transfer sessions, hands-on training on semiconductor equipment, and factory visits to observe real-world manufacturing workflows.

The team also participated in technical discussions and demonstrations related to process optimization, equipment handling, and quality control practices. Through these activities, the engineers gained practical exposure to advanced packaging methodologies and operational insights into state-of-the-art semiconductor manufacturing tools.



The training will continue to support technology localization, faster implementation of advanced packaging lines, and the strengthening of internal technical capabilities. The initiative also aligns with the broader goals of enhancing domestic semiconductor manufacturing capabilities under the Indian Semiconductor Mission and the 'Make in India' initiative.

# RRP Electronics Ltd. & HCLTech Sign an MoU to Advance Semiconductor Packaging and Testing Collaboration

A partnership announced at Vision Summit 2026 aims to strengthen India's backend semiconductor ecosystem.



## HCL tech MOU

**RRP Electronics Ltd.** has signed a Memorandum of Understanding with **HCLTech** at Vision Summit 2026. The partnership brings together RRP Electronics' semiconductor packaging and processing capabilities with HCLTech's testing and validation infrastructure. The collaboration aims to provide an integrated backend solutions including packaging, testing, and certification for customers across sectors including automotive, industrial electronics, telecommunications, and consumer applications.

As per the agreement, RRP Electronics' expertise in advanced semiconductor packaging such as QFN/DFN and BGA/LGA technologies will be combined

with HCLTech's test engineering and reliability capabilities. The initiative is designed to deliver a comprehensive backend assembly and test solution for semiconductor companies and electronics manufacturers.

Together, the collaborations represent a step toward building a more integrated semiconductor value chain in India, supporting the development of domestic backend manufacturing and testing capabilities.

The development was highlighted as a key milestone for HCLTech's Advanced Semiconductor Lab located in Electronics City Phase 2, Bengaluru.

# RRP Electronics Ltd. Participates in Vision Summit 2026 in Bengaluru

Industry event highlights emerging momentum in semiconductor and advanced electronics innovation

RRP Electronics Ltd. participated in Vision Summit 2026 held in Bengaluru on February 25<sup>th</sup> and 26<sup>th</sup> joined by industry leaders and technology experts to discuss emerging trends shaping the semiconductor and advanced electronics sectors.

At the two-day event, the company showcased its capability in Outsourced Semiconductor Assembly and Testing (OSAT), while engaging with industry stakeholders on the evolving technology landscape.

At the showcase, RRP Electronics Ltd.

highlighted its legacy semiconductor packaging solutions alongside advanced packaging technologies, including embedded die and flip-chip BGA assembly. It also presented its capabilities in SIM card and security IC technology, supported by full IP and process transfer, as well as integrated fingerprint module solutions designed for secure authentication. The display represented the company's focus on end-to-end semiconductor packaging and secure technology solutions.



## Chhatrapati Shivaji Maharaj Jayanti Celebrated at the Office

Chhatrapati Shivaji Maharaj Jayanti was observed at the office with a small gathering to mark the birth anniversary of Chhatrapati Shivaji Maharaj. The occasion commemorated his contribution to history and the values he stood for. The simple celebration highlighted respect for cultural heritage while bringing colleagues together in collective spirit.



## RRP Electronics Ltd. Marks Two Years with Employee Recognition and Team Celebration

On 22<sup>nd</sup> February, RRP Electronics Ltd. marked an important milestone two years since the company began its journey. It is exemplary of an ambitious vision that has, in a short span, grown into a company contributing to India's semiconductor and electronics ecosystem.

To celebrate the occasion, employees gathered at Gamera, a gaming arcade which enabled and encouraged them to interact beyond stipulated hours at work, cross functionally.

However, the highlight of the day was an internal program dedicated to recognizing employee contributions. 'Employee of the Month' certificates were presented, acknowledging individuals on the basis of strong professional commitment and performance. Individual teams also received accolades for having supported the company's growth.



The program also included the announcement of the winners of the internal "RRP King and Queen" activity. While the activity brought an element of fun and frolic to the gathering, it was also emblematic of the company's commitment to create a workplace culture that embraces values and team spirit.

The two-year milestone is a testament to the company's progress shaped by the dedication and collaboration of its teams.





**Harshwardhan Jadhav**

## Building Skills Through Global Exposure

Travelling to Taiwan for this training was a memorable experience for me, both professionally and personally. It was my first international visit for technical learning, and I was keen to make the most of it. Before the trip, I familiarized myself with advanced semiconductor packaging concepts and even picked up a few basic Chinese phrases, which proved quite handy along the way.

When I arrived at the facility, what immediately stood out was the scale and organization. The presence of multiple cleanrooms and advanced equipment reflected a highly structured manufacturing environment. As the training sessions began, the processes that initially seemed complex became much clearer through step-by-step demonstrations and hands-on explanations. One of the most memorable parts of the experience was interacting with the team at HorngCom Technology. While language was a challenge,

it also became a source of connection. We often relied on gestures, diagrams, and translation tools to communicate, and many of these moments turned into shared laughter. It created a positive and collaborative learning environment. One key takeaway was the value of a practical and solution-oriented mindset. Watching challenges being addressed with clarity and efficiency offered a fresh perspective that I look forward to applying in my work at RRP Electronics.

Experiencing the local culture added its own charm to the journey. The calm surroundings, polite nature of people, and their willingness to help made the stay comfortable and pleasant.

Overall, the experience brought together technical learning, collaboration, and cultural exposure in a balanced way. It reinforced the importance of adaptability and continuous learning, and I look forward to contributing towards taking RRP to new heights.

## Learning Beyond Expectations: A Training Experience in Taiwan

“The training program in Taiwan provided a valuable opportunity to gain hands-on exposure to semiconductor packaging processes in a real manufacturing environment. The experience offered practical insights into how processes are executed efficiently, with strong focus on precision and consistency.

From the beginning, the team was extremely supportive and welcoming, making every effort to ensure we understood the processes despite the language differences. Their willingness to share knowledge and guide us through each step made the learning experience both smooth and engaging.

One of the most memorable moments for me was observing the flip-chip bonding and moulding processes. What stood out was how efficiently these processes were executed. It highlighted those well-designed methods, when carried out with precision and experience, can deliver highly effective results.

A key takeaway from the training was the importance of simplicity in problem-solving. I realized that efficient manufacturing does not always rely on complexity, clear processes and skilled execution play an equally critical role. This perspective will certainly influence how I approach my work at RRP Electronics.

Beyond technical exposure, the visit also offered a chance to experience the local culture. Exploring places like temples, a memorial hall, and night markets added a meaningful dimension to the trip.

Overall, the training was a valuable experience that combined technical learning with practical insights. It provided a deeper understanding of semiconductor packaging processes and offered perspectives that will contribute to our work going forward.”

# RRP S4E Innovation (RRP Defense Ltd.)

## Surveillance Camera Deployment Completed for Strategic Security Project

RRP S4E Innovation recently completed the supply and deployment of advanced Pan-Tilt-Zoom (PTZ) surveillance cameras as part of a security infrastructure project for strategic defense.

The systems enable flexible monitoring through remote pan, tilt, and zoom capabilities, supporting enhanced situational awareness and improved surveillance coverage. The successful completion of the supply phase reflects the company's growing involvement in supporting critical monitoring and security infrastructure initiatives.



## Technology Spotlight: VIRAJ PTZ Surveillance Systems

RRP S4E Innovation develops advanced PTZ surveillance cameras under the VIRAJ series, designed for long-range monitoring in defense and security environments. The systems combine high-definition visible imaging with thermal capabilities to support day and night time operations.



### VIRAJ 28 SERIES

Models feature a dual-sensor PTZ system with continuous 360° pan and ±45° tilt, designed to meet MIL-STD JSS-55555 standards for rugged field conditions. The systems include a Full HD day camera with 30× optical zoom and an uncooled thermal sensor capable of detecting targets in fog, smoke, or darkness. They operate on 12/24 V DC power and support IP streaming through ONVIF 2.4 compliance.



### VIRAJ C-LR

Variant incorporates cooled sensor technology, a day camera, and an optional laser rangefinder, enabling extended detection ranges and improved performance in demanding environments.

These PTZ systems are designed for use in applications such as airports, border security, coastal monitoring, and other critical infrastructure environments where reliable, all-weather surveillance is required.

## RRP Team Recognized for Conducting Specialized Equipment Training

RRP S4E Innovation recently conducted a technical training program for end users as part of an equipment deployment project involving advanced night-vision-based sighting systems.

The training focused on providing operational understanding, correct handling procedures, and practical usage of the system to ensure effective field deployment. The program was designed to help users become familiar with the equipment and its operational capabilities.

The session was led by RRP S4E' training representatives **Neeraj Dohare** and **Karan Mane**, who guided participants through the technical and operational aspects of the system.

Following the completion of the program, both representatives received formal letters of appreciation from the client organization in recognition of their contribution and the effective conduct of the training session.

The acknowledgement highlights the successful completion of training associated with the equipment deployment, and reflects the company's continued focus on supporting users through technical guidance and knowledge transfer.



**Mr. Neeraj Dohare**



**Mr. Karan Mane**

## Thermal Imaging Equipment Deliveries Progress Under Industrial Order

RRP S4E Innovation is progressing with the execution of an order for Hand-Held Thermal Imagers (HHTI) received through an industrial partner.

As part of the order fulfillment process, the company completed the first phase of delivery with an initial shipment of the equipment. This was followed by an additional shipment delivered recently in line with the customer's requirements.

According to project updates, end users have provided positive feedback regarding the performance of the product and have noted its operational capabilities.

The deliveries mark continued progress in executing the order and highlight the company's role in providing advanced thermal imaging technologies for specialized applications.

## Technology Highlight: RRP S4E Innovation Hand-Held Thermal Imagers

RRP S4E Innovation develops Hand-Held Thermal Imagers (HHTI) as part of its thermal sights and imaging systems portfolio designed for defense, law enforcement, and security applications.

### PR110 MF

features an uncooled micro-bolometer sensor with 640×480 resolution and digital zoom up to 8×. The system combines thermal and low-light imaging to provide visibility through fog, smoke, or darkness. It includes extended battery life, integrated GPS and compass, image stabilization, and real-time data transmission. The device is portable and built to meet MIL-STD JSS-5555 ruggedization standards.



### PR82

uses a 12-micron 640×480 thermal sensor with 3× optical magnification and up to 4× digital zoom. It features an OLED display (800×600 resolution) with multiple lens options and is designed for reliable target detection in low-visibility or adverse weather conditions.

These systems are built for demanding operational environments where portable, high-performance thermal imaging is required.



# CREDITS

As we conclude this edition of our newsletter, we would like to take a moment to express our sincere gratitude to everyone who contributed to making it possible. This publication reflects the collective efforts, insights, and dedication of individuals across the organization who shared their time, updates, and achievements.

We extend our heartfelt appreciation to our leadership team for their continued guidance and vision. Their leadership and encouragement continue to shape the organization's growth and inspire our journey forward.

Our sincere thanks also go to the teams across **RRP Electronics Ltd.** and **RRP Defense Ltd.** whose cooperation and contributions helped bring together the stories, milestones, and updates featured in this edition.

This newsletter represents the shared progress of our organization, and we appreciate the support of everyone who contributed directly or indirectly. We look forward to sharing many more milestones and achievements in the editions to come as we continue building the future together.

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# RRP GROUP OF COMPANIES

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**FEBRUARY 2026**

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